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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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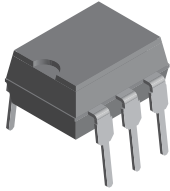
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

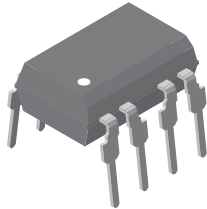


Optocoupler, Photodarlington Output, with Internal RBE (Single, Dual, Quad Channel)

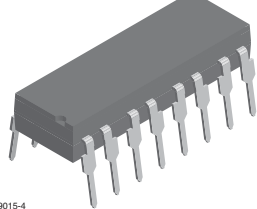
Single Channel



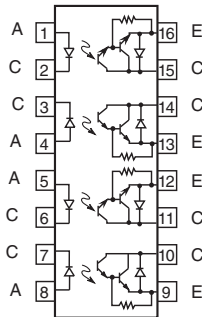
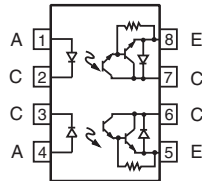
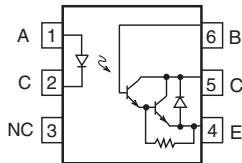
Dual Channel



Quad Channel



1179015-4



FEATURES

- Internal RBE for high stability
- Four available CTR categories per package type
- $BV_{CEO} > 60\text{ V}$
- Standard DIP packages
- Compliant to RoHS Directive 2002/95/EC and in accordance with WEEE 2002/96/EC



RoHS COMPLIANT

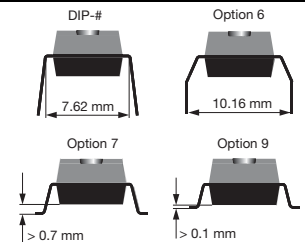
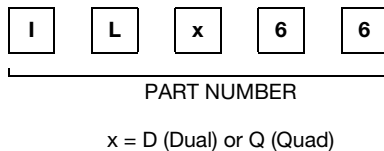
DESCRIPTION

IL66, ILD66, and ILQ66 are optically coupled isolators employing gallium arsenide infrared emitters and silicon photodarlington detectors. Switching can be accomplished while maintaining a high degree of isolation between driving and load circuits, with no crosstalk between channels.

AGENCY APPROVALS

- UL1577, file no. E52744 system code H, double protection
- cUL tested to CSA 22.2 bulletin 5A
- DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-5-5 pending available with option 1
- BSI IEC 60950; IEC 60065

ORDERING INFORMATION



| AGENCY CERTIFIED/PACKAGE | SINGLE CHANNEL | | DUAL CHANNEL | | QUAD CHANNEL | | | |
|--------------------------|----------------|--------|--------------|--------------|--------------|---------|---------|--------------|
| | CTR (%) | | | | | | | |
| | 2 mA | | | | 0.7 mA | | 2 mA | |
| UL, cUL, BSI | ≥ 100 | ≥ 300 | ≥ 300 | ≥ 500 | ≥ 100 | ≥ 300 | ≥ 400 | ≥ 500 |
| DIP-4 | IL66-1 | IL66-2 | - | - | - | - | - | - |
| DIP-8 | - | - | ILD66-2 | ILD66-4 | - | - | - | - |
| SMD-8, option 7 | - | - | - | ILD66-4X007T | - | - | - | - |
| SMD-8, option 9 | - | - | - | ILD66-4X009 | - | - | - | - |
| DIP-16 | - | - | - | - | ILQ66-1 | ILQ66-2 | ILQ66-3 | ILQ66-4 |
| SMD-16, option 7 | - | - | - | - | - | - | - | ILQ66-4X007T |
| SMD-16, option 9 | - | - | - | - | - | - | - | ILQ66-4X009T |
| VDE, UL, cUL, BSI | ≥ 100 | ≥ 300 | ≥ 300 | ≥ 500 | ≥ 100 | ≥ 300 | ≥ 400 | ≥ 500 |
| DIP-4, 400 mil, option 6 | IL66-1X016 | | | | | | | |
| DIP-16 | | | | | | | | ILQ66-4X001 |

Note

- Additional option may be possible, please contact sales office.



| ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | |
|--|--|-------|------------|----------------|-----------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | VALUE | UNIT |
| INPUT | | | | | |
| Peak reverse voltage | | | V_{RM} | 6.0 | V |
| Forward continuous current | | | I_F | 60 | mA |
| Power dissipation | | | P_{diss} | 100 | mW |
| Derate linearly from 25 °C | | | | 1.33 | mW/°C |
| OUTPUT | | | | | |
| Power dissipation | | | P_{diss} | 150 | mW |
| Derate from 25 °C | | | | 2.0 | mW/°C |
| COUPLER | | | | | |
| Isolation test voltage | $t = 1.0\text{ s}$ | | V_{ISO} | 5300 | V_{RMS} |
| Total package power dissipation | | IL66 | P_{tot} | 250 | mW |
| | | ILD66 | P_{tot} | 400 | mW |
| | | ILQ66 | P_{tot} | 500 | mW |
| Derate linearly from 25 °C | | IL66 | | 3.3 | mW/°C |
| | | ILD66 | | 5.33 | mW/°C |
| | | ILQ66 | | 6.67 | mW/°C |
| Creepage distance | | | | ≥ 7.0 | mm |
| Clearance distance | | | | ≥ 7.0 | mm |
| Comparative tracking index | | | CTI | 175 | |
| Isolation resistance | $V_{IO} = 500\text{ V}, T_{amb} = 25\text{ }^{\circ}\text{C}$ | | R_{IO} | $\geq 10^{12}$ | Ω |
| | $V_{IO} = 500\text{ V}, T_{amb} = 100\text{ }^{\circ}\text{C}$ | | R_{IO} | $\geq 10^{11}$ | Ω |
| Storage temperature | | | T_{stg} | - 55 to + 125 | °C |
| Operating temperature | | | T_{amb} | - 55 to + 100 | °C |
| Lead soldering time at 260 °C | | | | 10 | s |

Note

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

| ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | |
|--|--|-------------|------|------|------|---------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| INPUT | | | | | | |
| Forward voltage | $I_F = 20\text{ mA}$ | V_F | | 1.25 | 1.5 | V |
| Reverse current | $V_R = 6.0\text{ V}$ | I_R | | 0.1 | 10 | μA |
| Capacitance | $V_R = 0\text{ V}$ | C_O | | 25 | | pF |
| OUTPUT | | | | | | |
| Collector emitter breakdown voltage | $I_C = 1.0\text{ mA}, I_F = 0\text{ A}$ | BV_{CEO} | 60 | | | V |
| Collector base breakdown voltage (IL66) | $I_C = 10\text{ }\mu\text{A}$ | BV_{CBO} | 60 | | | V |
| Collector emitter leakage current | $V_{CE} = 50\text{ V}, I_F = 0\text{ A}$ | I_{CEO} | | 1.0 | 100 | nA |
| Capacitance collector emitter | $V_{CE} = 10\text{ V}$ | | | 3.4 | | pF |
| COUPLER | | | | | | |
| Saturation voltage, collector emitter | $I_C = 10\text{ mA}, I_F = 10\text{ mA}$ | V_{CEsat} | | 0.9 | 1.0 | V |

Note

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

| CURRENT TRANSFER RATIO ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | | |
|--|---|-------------|--------|------|------|------|------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Current transfer ratio | $I_F = 2.0\text{ mA}$, $V_{CE} = 10\text{ V}$ | IL(D,Q)66-1 | CTR | 100 | 400 | | % |
| | | IL(D,Q)66-2 | CTR | 300 | 500 | | % |
| | $I_F = 0.7\text{ mA}$, $V_{CE} = 10\text{ V}$ | IL(D,Q)66-3 | CTR | 400 | 500 | | % |
| | $I_F = 2.0\text{ mA}$, $V_{CE} = 5.0\text{ V}$ | IL(D,Q)66-4 | CTR | 500 | 750 | | % |

| SWITCHING CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | | |
|---|--|--------|------|------|------|---------------|--|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT | |
| NON SATURATED | | | | | | | |
| Rise time -1, -2, -4 | $V_{CC} = 10\text{ V}$, $I_F = 2.0\text{ mA}$, $R_L = 100\text{ }\Omega$ | t_r | | | 200 | μs | |
| Fall time -1, -2, -4 | $V_{CC} = 10\text{ V}$, $I_F = 2.0\text{ mA}$, $R_L = 100\text{ }\Omega$ | t_f | | | 200 | μs | |
| Rise time -3 | $V_{CC} = 10\text{ V}$, $I_F = 0.7\text{ mA}$, $R_L = 100\text{ }\Omega$ | t_r | | | 200 | μs | |
| Fall time -3 | $V_{CC} = 10\text{ V}$, $I_F = 0.7\text{ mA}$, $R_L = 100\text{ }\Omega$ | t_f | | | 200 | μs | |

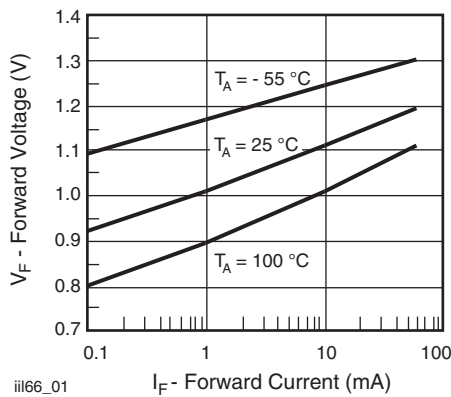
TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Forward Voltage vs. Forward Current

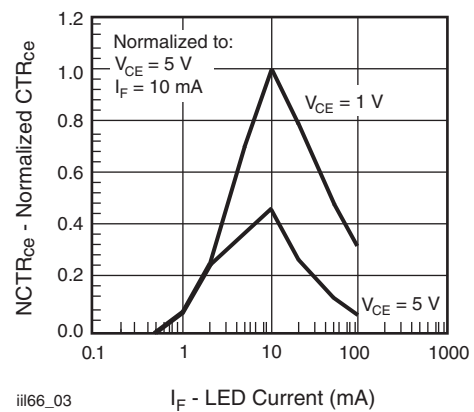
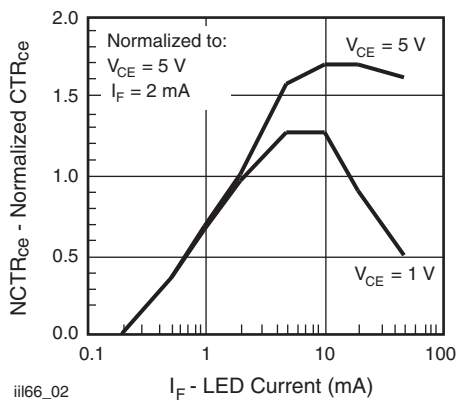
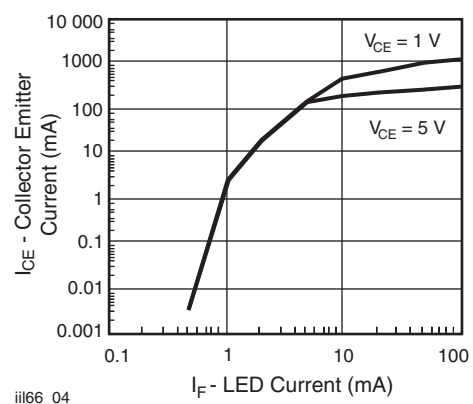

 Fig. 3 - Normalized Non-Saturated and Saturated CTR_{ce} vs. LED Current

 Fig. 2 - Normalized Non-Saturated and Saturated CTR_{ce} vs. LED Current


Fig. 4 - Non-Saturated and Saturated Collector Emitter Current vs. LED Current

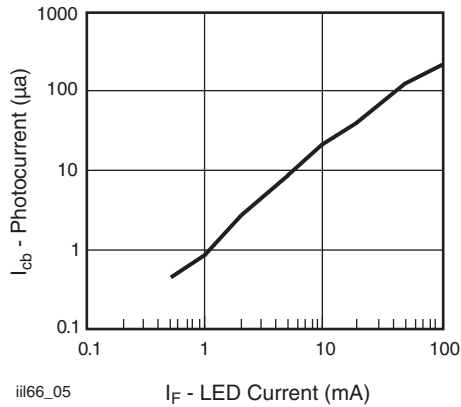


Fig. 5 - Collector Base Photocurrent vs. LED Current

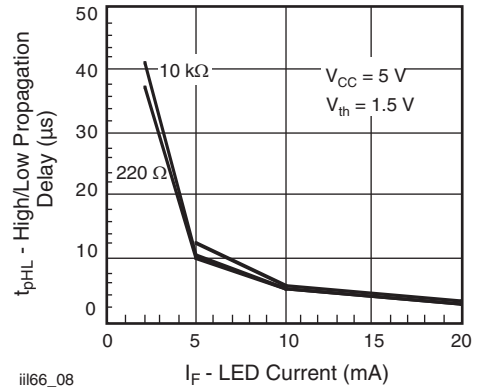


Fig. 8 - High to Low Propagation Delay vs. Collector Load Resistance and LED Current

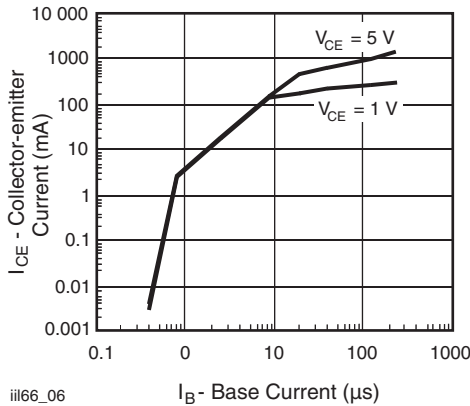


Fig. 6 - Collector Emitter Current vs. LED Current

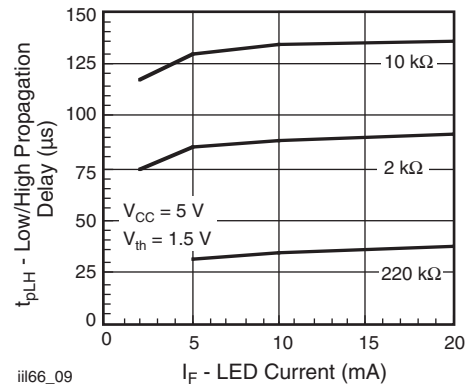


Fig. 9 - Low to High Propagation Delay vs. Collector Load Resistance and LED Current

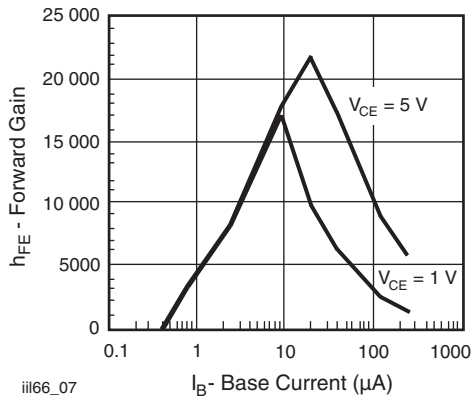


Fig. 7 - Non-Saturated and Saturated h_{FE} vs. LED Current

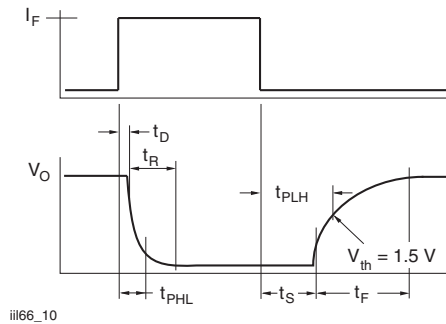


Fig. 10 - Switching Waveform

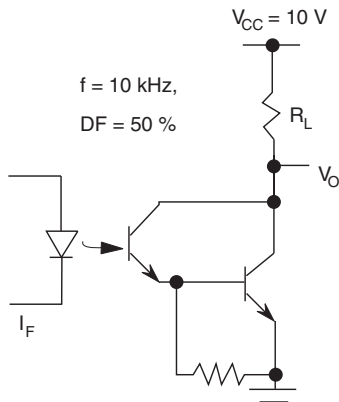
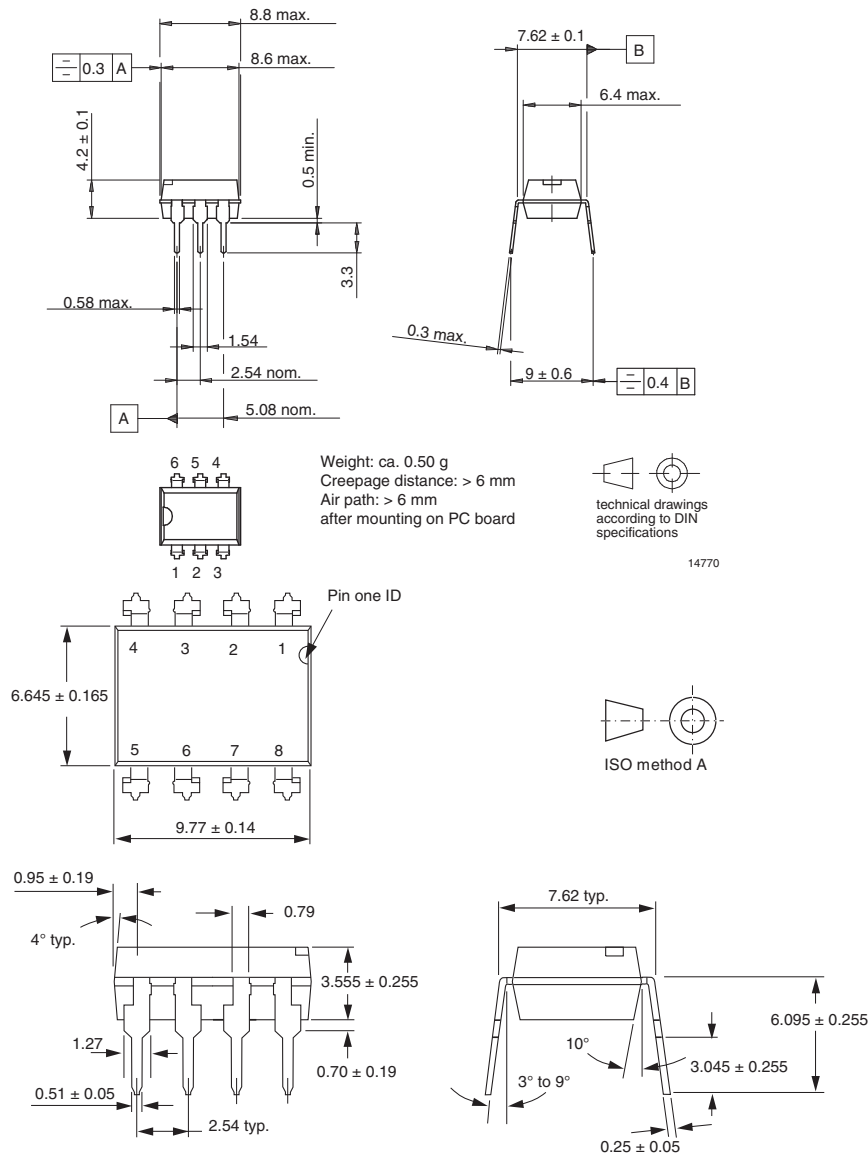
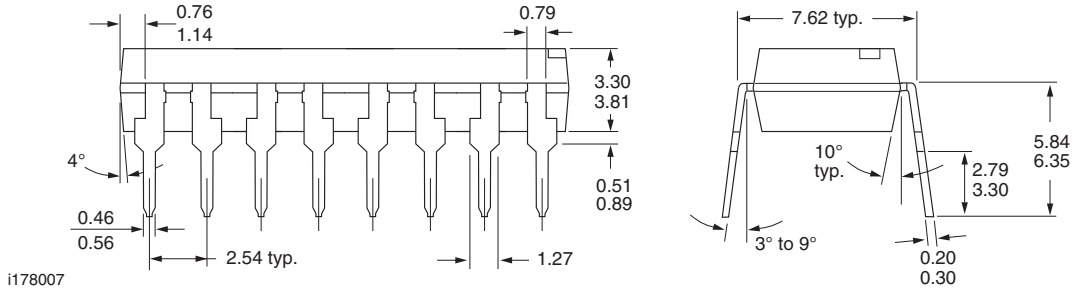
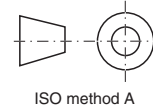
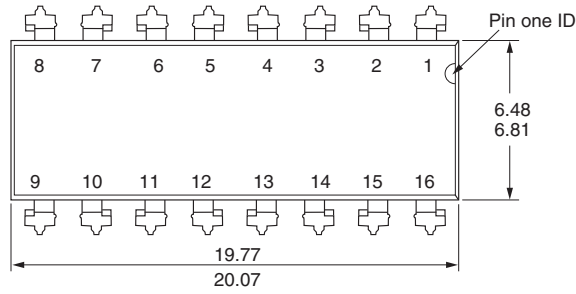


Fig. 11 - Switching Schematic

PACKAGE DIMENSIONS in millimeters

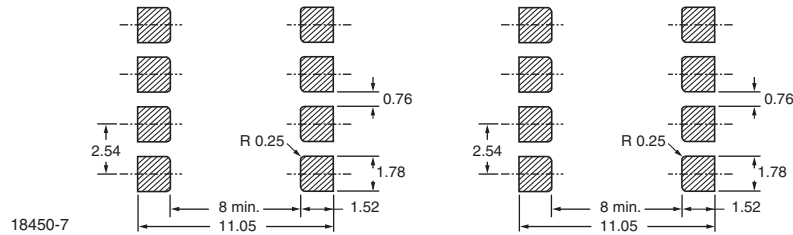
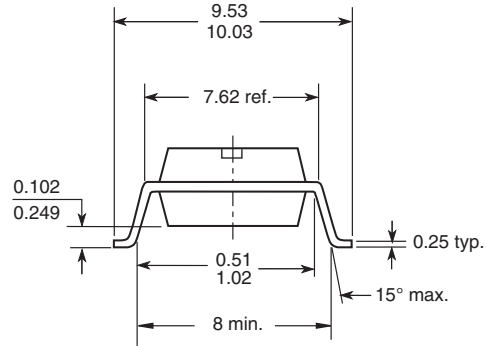
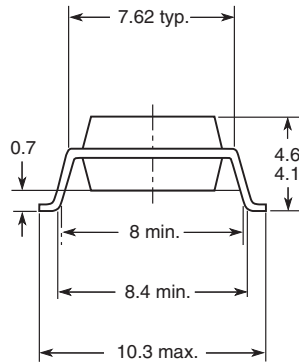




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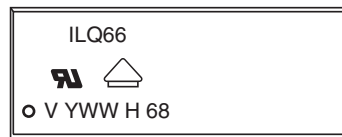
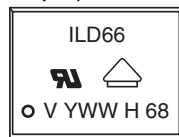
Option 7

Option 9



18450-7

PACKAGE MARKING (example)

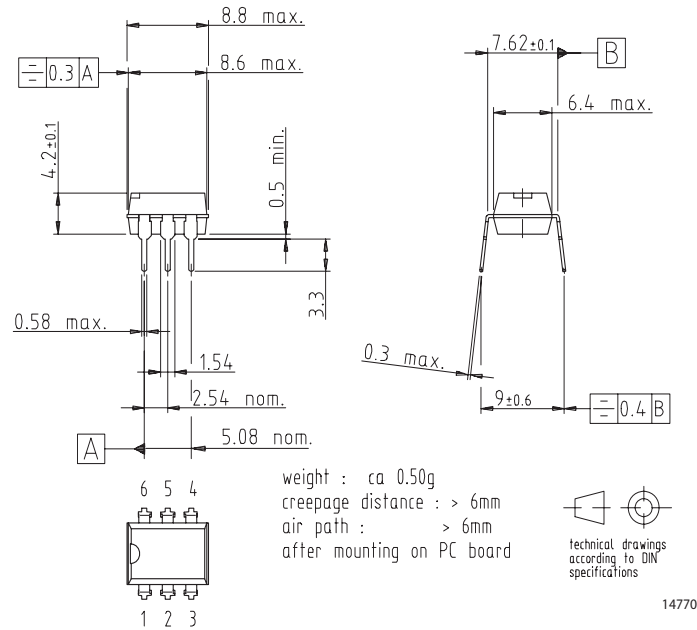


Notes

- Only options 1 and 7 reflected in the package marking
- The VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

DIL300-6

Package Dimensions in mm



Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design
and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

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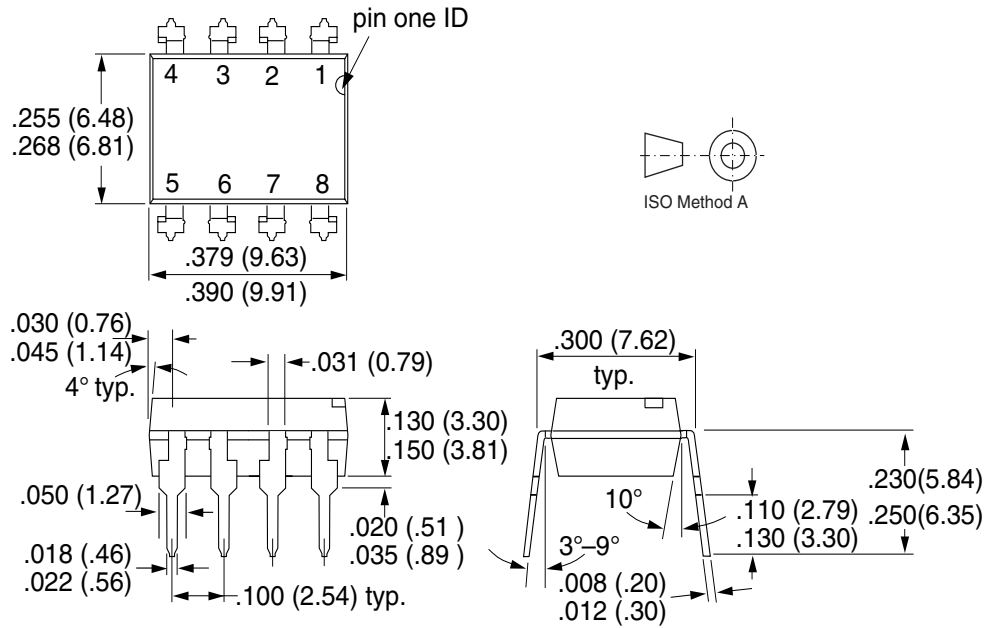
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Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

DIP-8

Package Dimensions in Inches (mm)



i178006

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Footprints

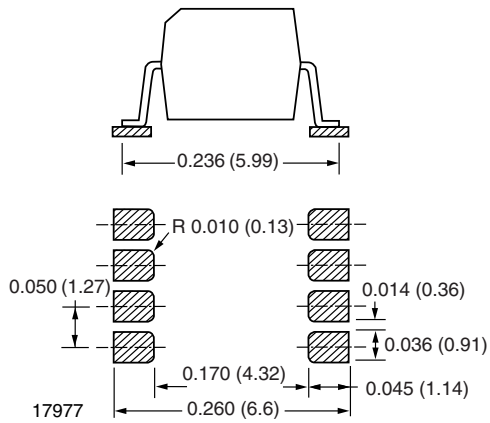
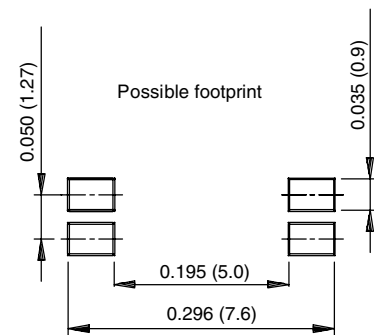
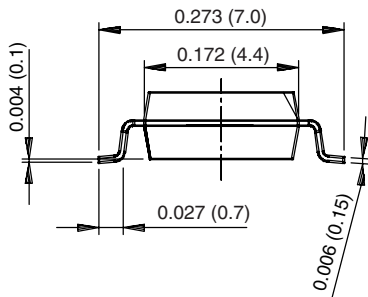
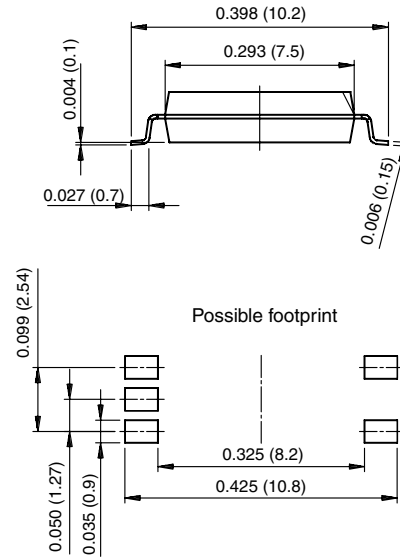


Fig. 1 - SO8A and DSO8A SMD



18403

Fig. 2 - SOP-4, Miniflat



18406

Fig. 3 - SOP-6, 5 Pin Wide Body

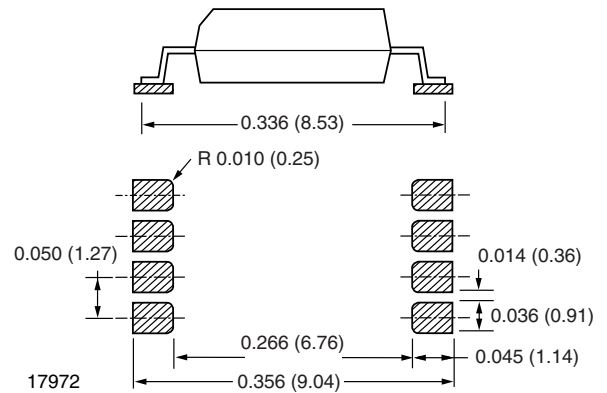


Fig. 4 - 8 Pin PCMCIA

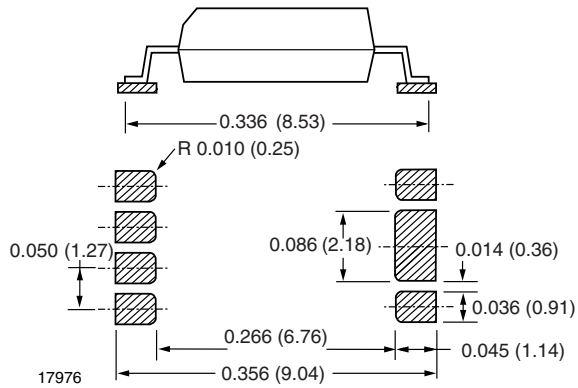


Fig. 5 - 8 Pin PCMCIA, Heat Sink

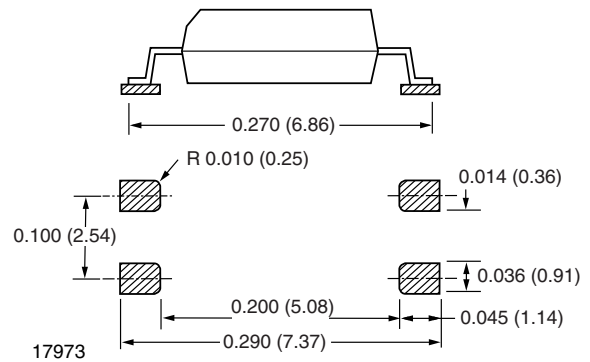


Fig. 8 - 4 Pin Mini-Flat

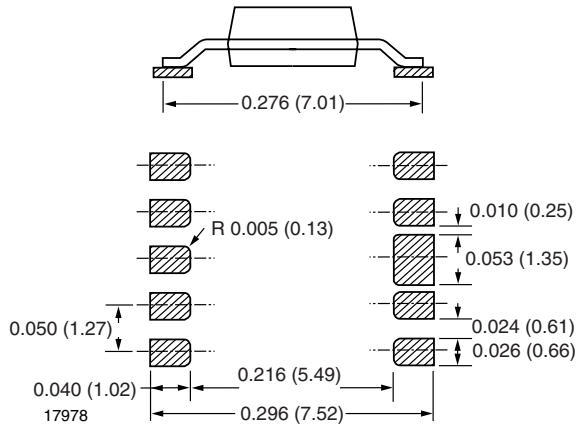


Fig. 6 - Mini Coupler

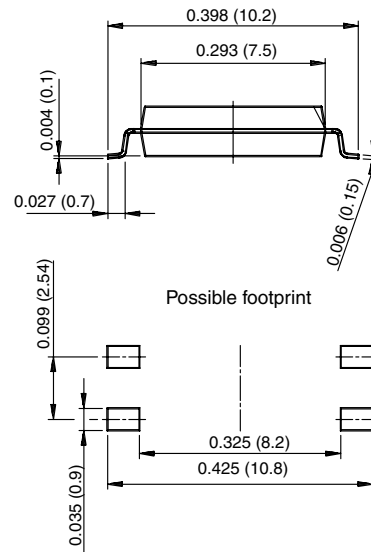


Fig. 9 - SOP-6, 4 Pin Wide Body

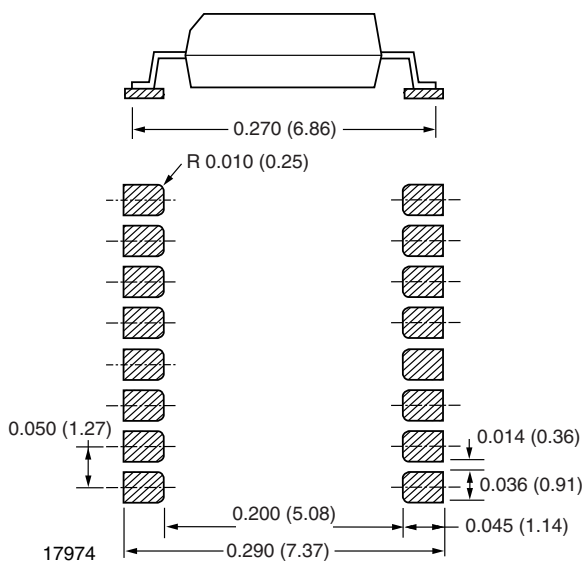


Fig. 7 - SOP-16

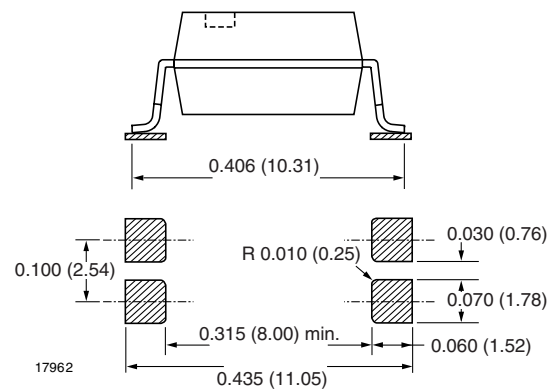


Fig. 10 - 4 Pin SMD Option 7

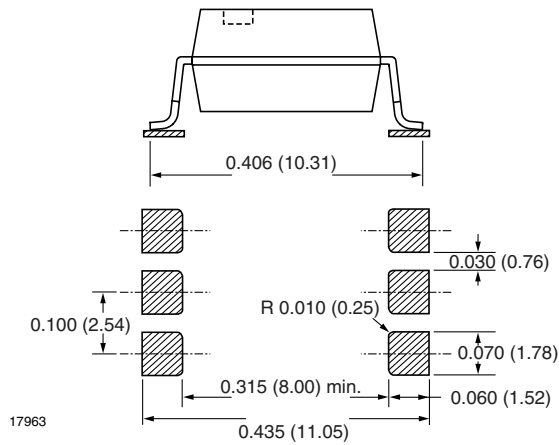


Fig. 11 - 6 Pin SMD Option 7

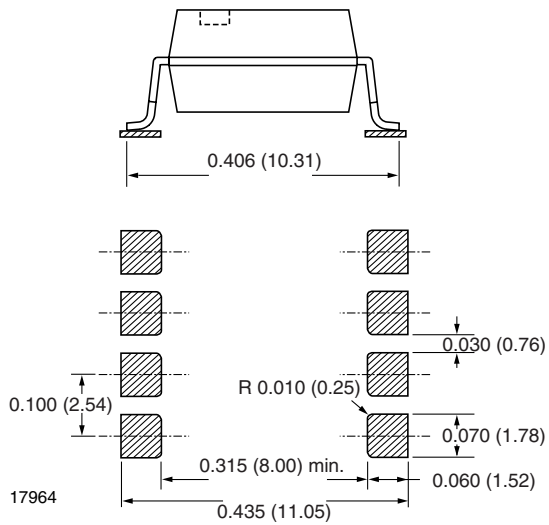


Fig. 12 - 8 Pin SMD Option 7

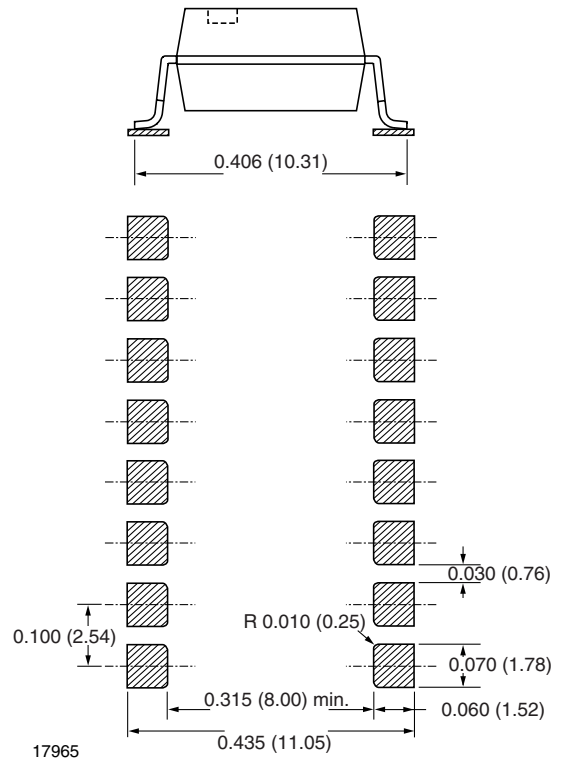


Fig. 13 - 16 Pin SMD Option 7

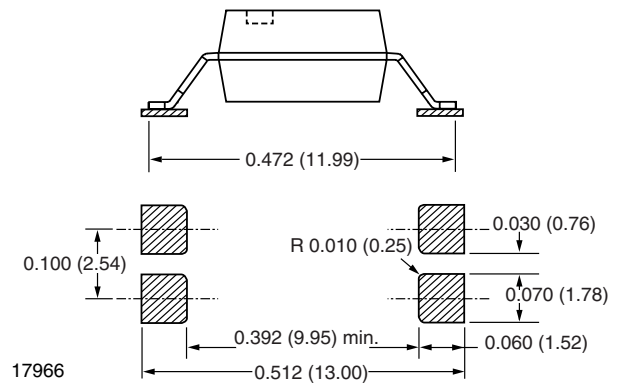


Fig. 14 - 4 Pin SMD Option 8

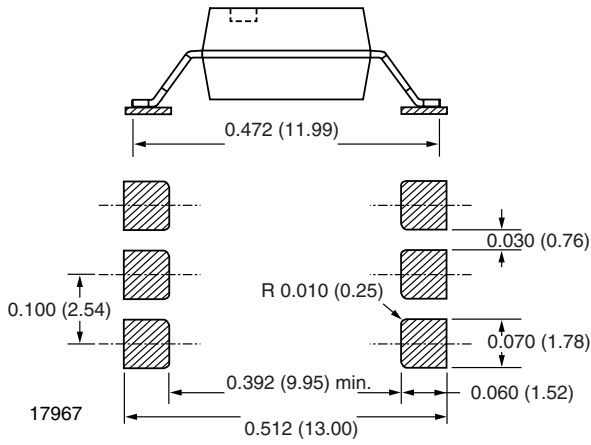


Fig. 15 - 6 Pin SMD Option 8

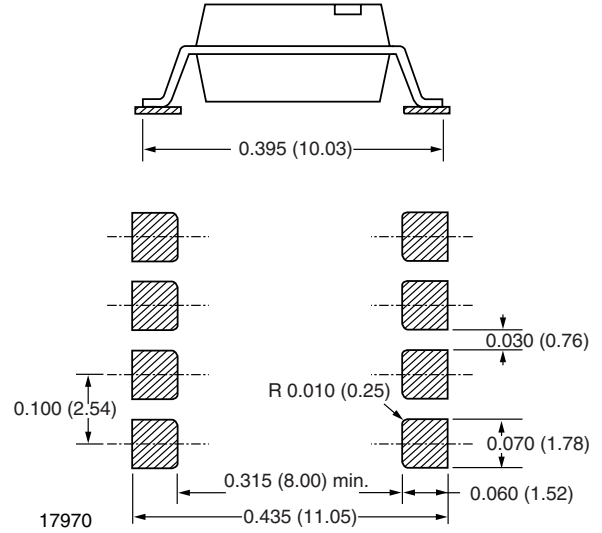


Fig. 18 - 8 Pin SMD Option 9

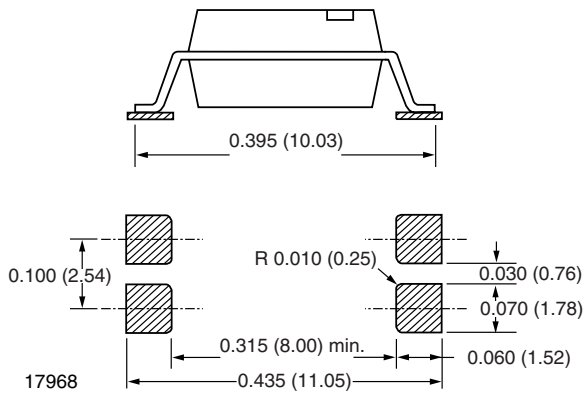


Fig. 16 - 4 Pin SMD Option 9

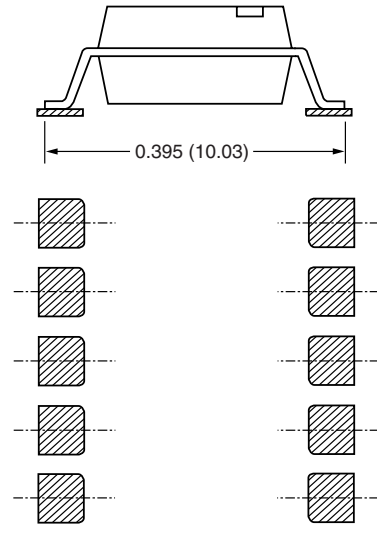


Fig. 19 - 16 Pin SMD Option 9

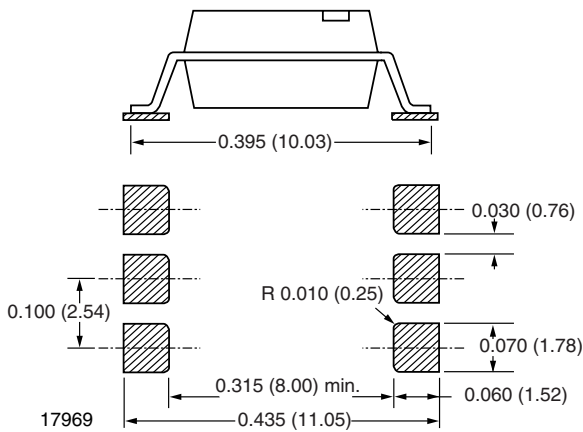


Fig. 17 - 6 Pin SMD Option 9

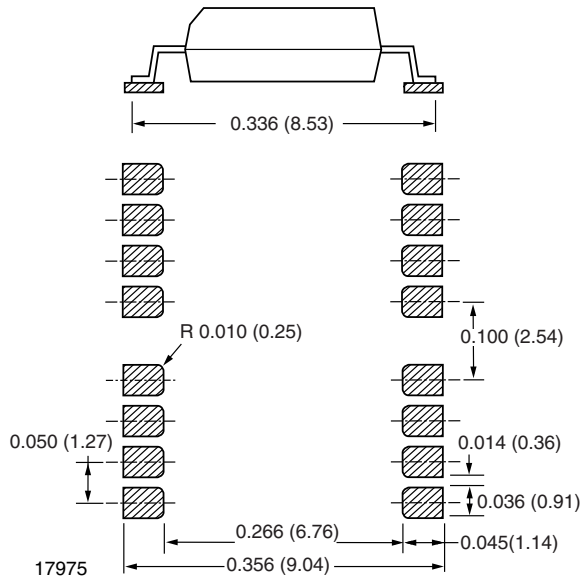


Fig. 20 - 16 Pin PCMCIA



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